

LISTING OF CLAIMS

1. (withdrawn) A display device comprising:
a display panel having electrode wiring;
a circuit board for supplying voltage to said electrode wiring;
a sheet material for electrically connecting said electrode wiring to said circuit board;
a frame for holding said display panel; and
a restraint member for restraining said circuit board, said sheet material and said frame from moving relatively from one to another in a plane direction.
2. (withdrawn) The display device according to claim 1, wherein said restraint member is located in a path region of substantial propagation of stress resulting from a difference in coefficients of linear expansion between glass substrates constituting said display panel and said circuit board.
3. (withdrawn) The display device according to claim 1, wherein said restraint member has a function of determining the relative positions of said circuit board, said sheet material and said frame.

4. (currently amended) A liquid crystal display device comprising:

a liquid crystal display panel comprising a pair of glass substrates facing each other, each having electrodes for applying voltage to a liquid crystal material on a facing surface;

a circuit board for supplying said voltage; and
a liquid crystal driver tape carrier package for connecting said electrodes of said glass substrates to said circuit board and mounting ~~a~~ at least one liquid crystal driver chip,

wherein said liquid crystal driver tape carrier package and said circuit board each have more than two anchor holes located on a first side in a path region of substantial propagation of stress resulting from a difference in coefficients of linear expansion between the glass substrates comprising ~~constituting~~ the liquid crystal display panel and the circuit board and wherein at least one pair of anchor holes on said liquid crystal driver tape carrier package are located with one of said at least one liquid crystal driver chip between said pair of anchor holes, and

more than two anchor pins are inserted, one pin into each of said more than two anchor holes, whereby said liquid crystal driver tape carrier package is soldered to said circuit board via said anchor pins and is restrained from movement due to said stress.

5. (original) The liquid crystal display device according to claim 4 further comprising a frame for allowing said anchor pins to stand on a surface holding said pair of glass substrates, wherein said liquid crystal driver tape carrier package and said circuit board are fixed to said frame.

6. (currently amended) The liquid crystal display device according to claim 4, said liquid crystal driver tape carrier package and said circuit board each have more than two additional anchor holes located on a second side adjacent to said first side and wherein at least one pair of said additional anchor holes is located with one of said at least one liquid crystal driver chip between.

7. (previously presented) The liquid crystal display device according to claim 5, wherein said anchor pins are conductive, and wherein a grounding conductor is formed on said frame, and said conductive anchor pins are conductively connected to said grounding conductor.

8. (canceled)

9. (withdrawn) A method of manufacturing a liquid crystal display device comprising glass substrates having electrodes wired for driving a liquid crystal material, a circuit board, and a sheet material having a conducting path, said glass substrates being conductively connected to said circuit board through said sheet material, said method comprising the steps of:

mounting said sheet material having through holes in a predetermined region on said glass substrates;

positioning said circuit board having through holes at positions corresponding to the through holes of said sheet material so as to align the through holes of said circuit board with the through holes of said sheet material;

restraining said sheet material and said circuit board from moving at least in a plane direction through the through holes of said sheet material and the through holes of said circuit board, thereby fixing said sheet material and said circuit board; and

restraining said sheet material and said circuit board from moving relative to a frame for holding said glass substrates at least in the plane direction through the through holes of said sheet material and said circuit board, thereby fixing said sheet material and said circuit board.

10. (withdrawn) The method of manufacturing a liquid crystal display device according to claim 9, wherein said restraining step further includes the step of inserting pins into the through holes of said sheet material and the through holes of said circuit board.

11. (withdrawn) The method of manufacturing a liquid crystal display device according to claim 10, wherein said restraining step further includes the step of inserting said pins into pin holding holes of said frame.

12. (withdrawn) The method of manufacturing a liquid crystal display device according to claim 9, further

includes the steps of providing an outer periphery of each of said pins with solder, inserting said pins into the through holes of said sheet material and the through holes of said circuit board, and soldering said sheet material to said circuit board by heating said pins.

13. (withdrawn) A method of connecting a display panel to a circuit board in a display device comprising said display panel having electrode wiring, a frame for holding said display panel and said circuit board, comprising the steps of:

connecting said display panel to said circuit board through a sheet material having a conducting path, and restraining said sheet material and said circuit board from moving relative to said frame in a plane direction.

14. (withdrawn) The connecting method according to claim 13, wherein said restraining step further includes the step of inserting pins standing in said frame into through holes formed in predetermined regions of said sheet material and said circuit board, whereby said sheet material and said circuit board are restrained from moving.

15. (withdrawn) The connecting method according to claim 14, further includes the step of defining said predetermined region as a path region of substantial propagation of stress resulting from a difference in coefficients of linear expansion between glass substrates constituting said display panel and said circuit board.